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For Continued Examination (RCE) **Transmittal**

Address to: Commissioner for Patents Box RCE Washington, DC 20231

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Application Number	10/080,468	
Filing Date	February 22, 2002	
First Named Inventor	Hua Ji # 16 RC	E
Art Unit	2814 JA Ba	insm
Examiner Name	Anh D. Mai	2
Attorney Docket Number	M-12589 US	08-

This is a Request for Continued Examination (RCE) under 37 CFR 1.114 of the above-identified application. Request for Continued Examination (RCE) practice under 37 CFR 1.114 does not apply to any utility or plant application filed prior to June 8, 1995, or to any design application. See Instruction Sheet for RCEs (not to be submitted to the USPTO) on page 2.

1.	Submission required under 37 CFR 1.114						
	a.		Previously submitted				
		i.	Consider the amendment(s)/reply under 37 CFR 1.116 previously filed on (Any unentered amendment(s) referred to above will be entered).	•			
		li.	Consider the arguments in the Appeal Brief or Rely Brief previously filed on				
		lii.	Other				
	b.	~	Enclosed				
		1.	Amendment/Reply iii. Information Disclosure Statement (IDS)			ı	
,		ii.	Affidavit(s)/ Declaration(s) iv. Other Return postcard			-	
2.	Mi	iscella	aneous				
	а.	П	Suspension of action on the above-identified application is requested under 37 CFR 1.103(c) for a period of months. (Period of suspension shall not exceed 3 months: Fee under 37 CFR 1.17(i) required)			ł	
	b.	\exists	period of months. (Period of suspension shall not exceed 3 months; Fee under 37 CFR 1.17(i) required) Other	_ •			
3.	Fo	ees	The RCE fee under 37 CFR 1.17(e) is required by 37 CFR 1.114 when the RCE is filed. The Director is hereby authorized to charge the following fees, or credit any overpayments, to Deposit Account No. 50-2257				
		i.	RCE fee required under 37 CFR 1.17(e)	γ2(× 2	<u>''</u>	
		ii.	Extension of time fee (37 CFR 1.136 and 1.17)	CE)	S		
		iii.	Other	Ī	2003		
	b.		Check in the amount of \$enclosed	R 28	w	4	
	c.		Payment by credit card (Form PTO-2038 enclosed)	2800			
		_	WARNING: Information on this form may become public. Credit card information should not be Included on this form. Provide credit card information and authorization on PTO-2038.				

	SIGNATURE OF APPLICANT,	ATTORNEY, OR AGENT REQUIRED
Name (Print/Type)	David S. Park	Registration No. (Attorney/Agent) 52,094
Signature	Cit 4. 122	Date April 21, 2003
	CERTIFICATE OF MA	ILING OR TRANSMISSION
I hereby certify that t addressed to: Comm shown below.	his correspondence is being deposited with the United Statissioner For Patents, Box RCE, Washington, DC 20231, EXPLESS MAIL LAVEL NO	ates Postal Service with sufficient postage as first class mail in an envelope or facsimile transmitted to the U.S. Patent and Trademark Office on the date
Name (Print/Type)		
Signature		Date April 21, 2003
	D.	one Lof 2

This collection of information is required by 37 CFR 1.114. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, Box RCE, Washington, DC 20231.

If you need assistance in completing the form, call 1-800-PTO-9199 (1-800-786-9199) and select option 2.



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s):

Hua Ji

Assignee:

Mosel Vitelic, Inc.

Title:

HDP CVD Process For Void-Free Gap Fill Of A High Aspect Ratio

Trench

Serial No.:

10/080,468

Filing Date:

February 22, 2002

Examiner:

Anh D. Mai

Group Art Unit:

2814 # 17C AMOT

Docket No.:

M-12589US

Irvine, California April 21, 2003

COMMISSIONER FOR PATENTS

Washington, D.C. 20231

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A, D.C. 20231

REQUEST FOR CONTINUED EXAMINATION SUBMISSION

Dear Sir:

In response to the Final Office Action dated November 20, 2002, and Agivisory Action dated April 9, 2003, Applicant requests continued examination and submits the following amendments and remarks.

IN THE SPECIFICATION

Please replace the following paragraph. A marked-up version showing the changes is included as Attachment A.

Please replace the paragraph on page 8, line 3 through line 22, with the following replacement paragraph:

CI

In addition to a reduced oxygen to silane ratio, the method of the present invention allows for low etch-to-deposition (E/D) ratios, corresponding to greater gap-fill capability. An E/D ratio is defined by the equation:

E/D = (UBUC-BUC)/UBUC